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(12) **United States Design Patent**
Tani et al.

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(54) **GROOVES FORMED AROUND A SEMICONDUCTOR DEVICE ON A CIRCUIT BOARD**

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(**) Term: **14 Years**

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Related U.S. Application Data

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(30) **Foreign Application Priority Data**

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May 1, 2006 (JP) 2006-011445
May 1, 2006 (JP) 2006-011446

(51) **LOC (9) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
174/250, 251, 253, 254, 255, 256, 265, 260,
174/261; 361/760, 748, 720; 336/200
See application file for complete search history.

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(57) **CLAIM**

The ornamental design for grooves formed around a semiconductor device on a circuit board, as shown and described.

DESCRIPTION

FIG. 1 shows a plan view of the grooves formed around a semiconductor on a circuit board showing the design according to the invention.

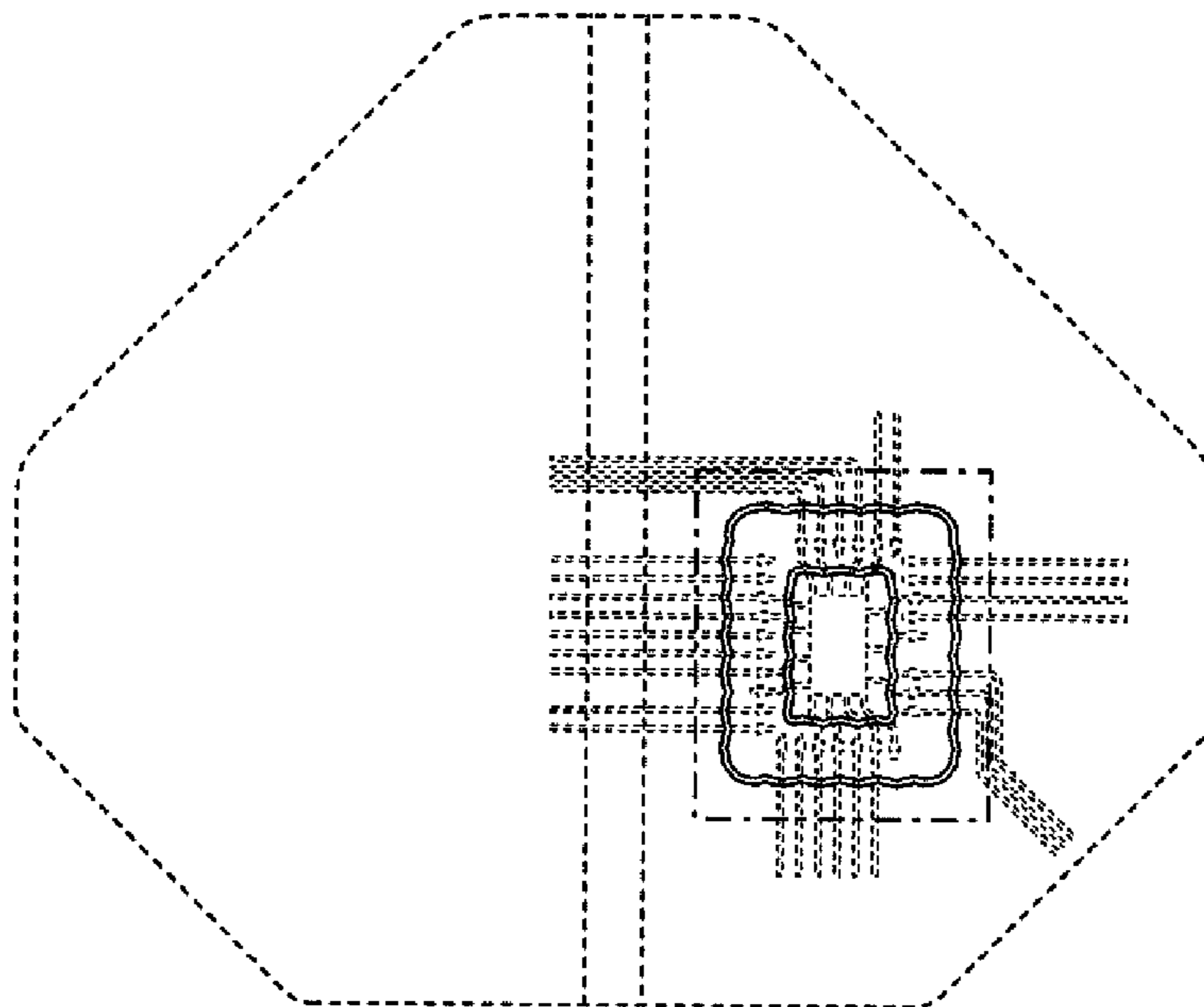
FIG. 2 shows an enlarged view of a claimed portion as identified by the area boxed by the dash-dot-dash line in FIG. 1.

FIG. 3 shows an enlarged sectional view along the line 3—3 in FIG. 2; and,

FIG. 4 shows an enlarged sectional view along the line 4—4 in FIG. 2.

The elements shown in broken lines and dash-dot-dash lines are for illustrative purposes only and form no part of the claimed invention.

1 Claim, 2 Drawing Sheets



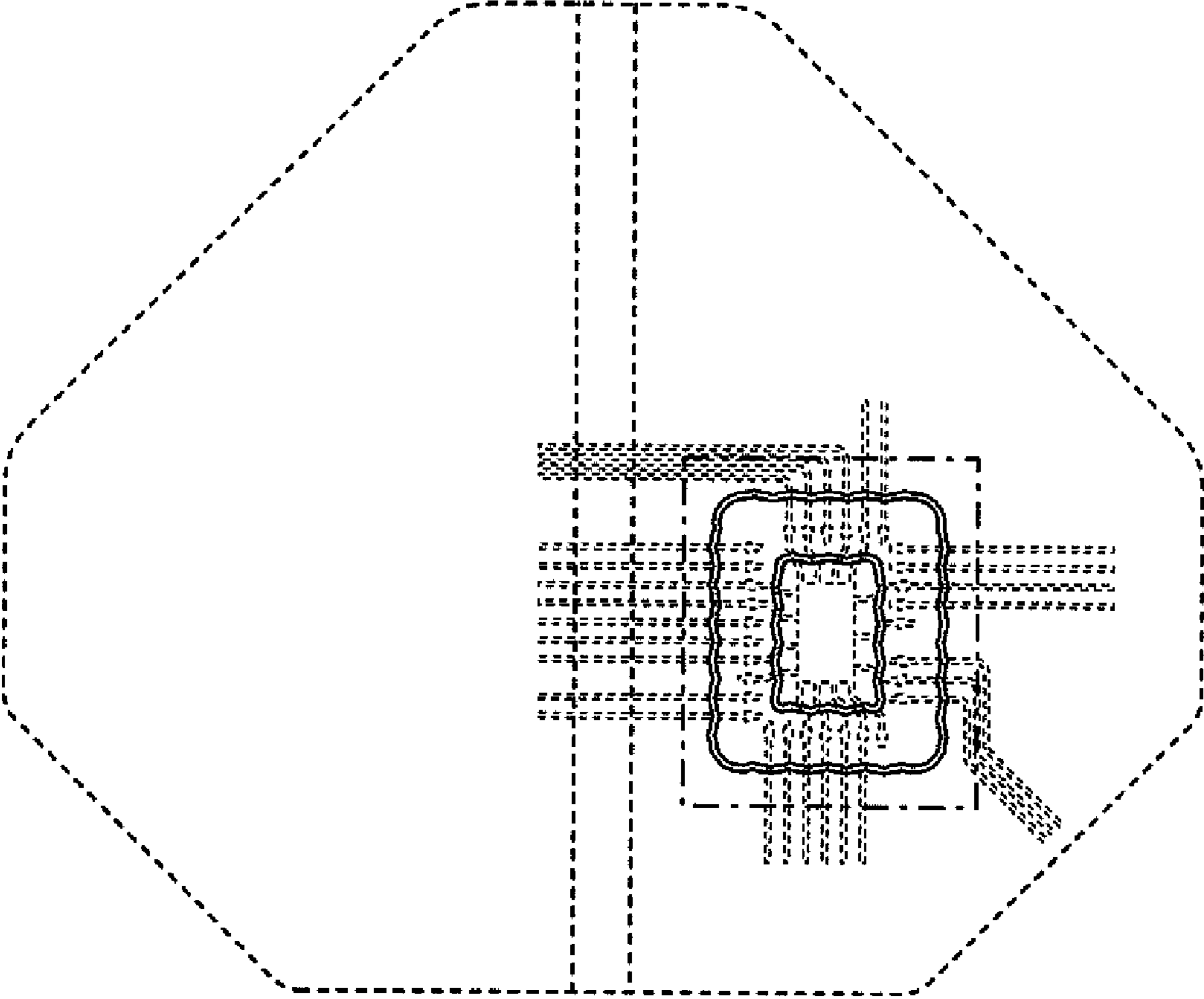


FIG. 1

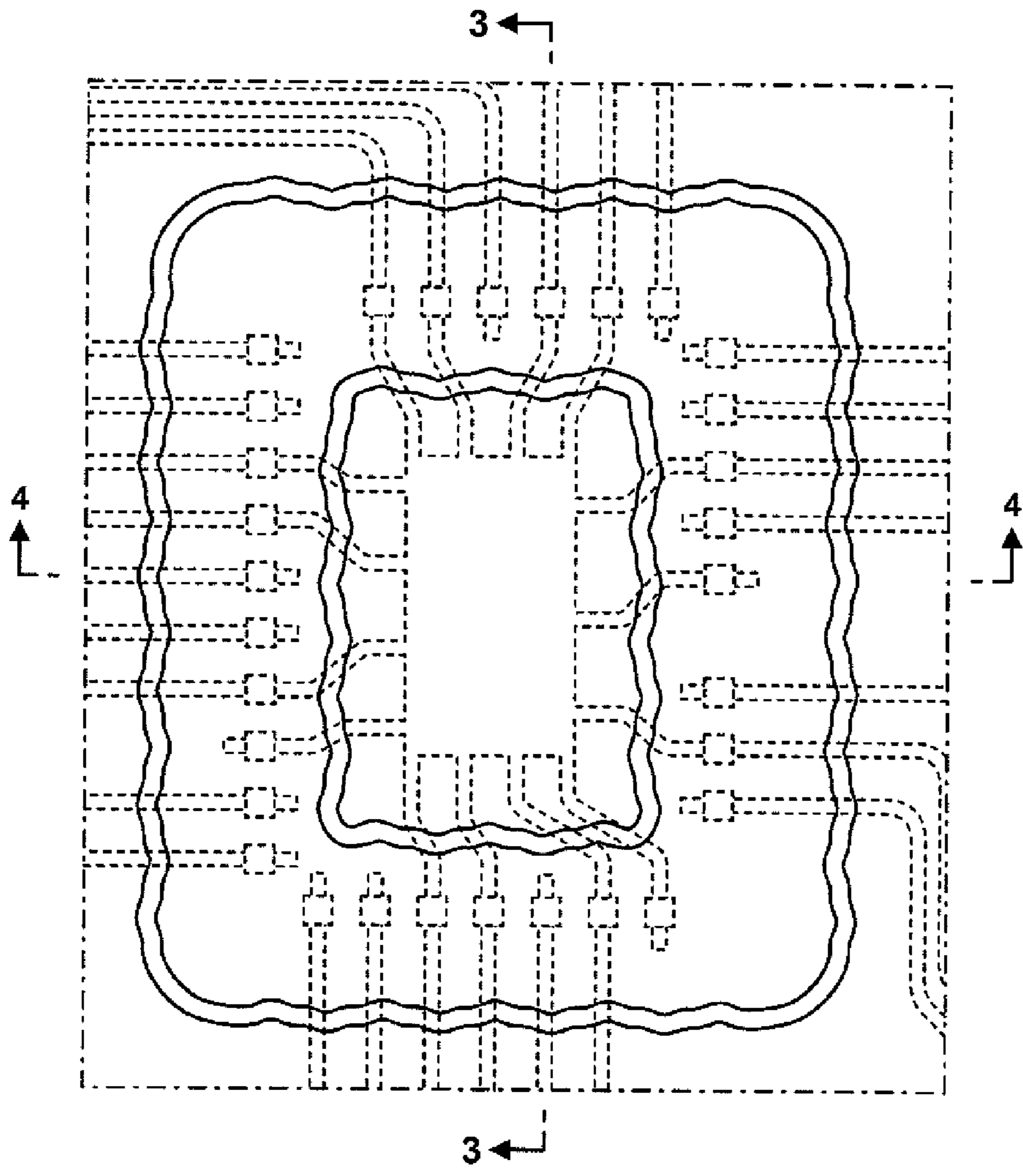


FIG. 2



FIG. 3

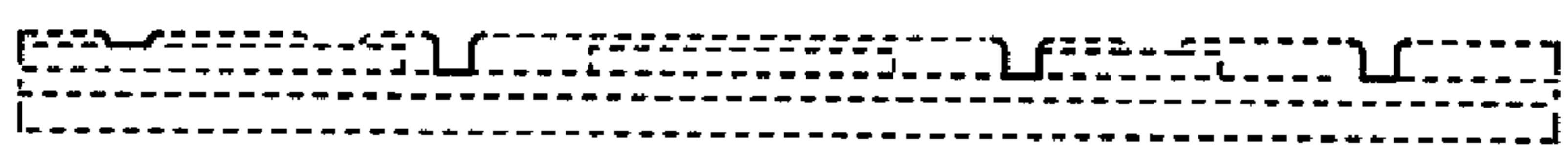


FIG. 4